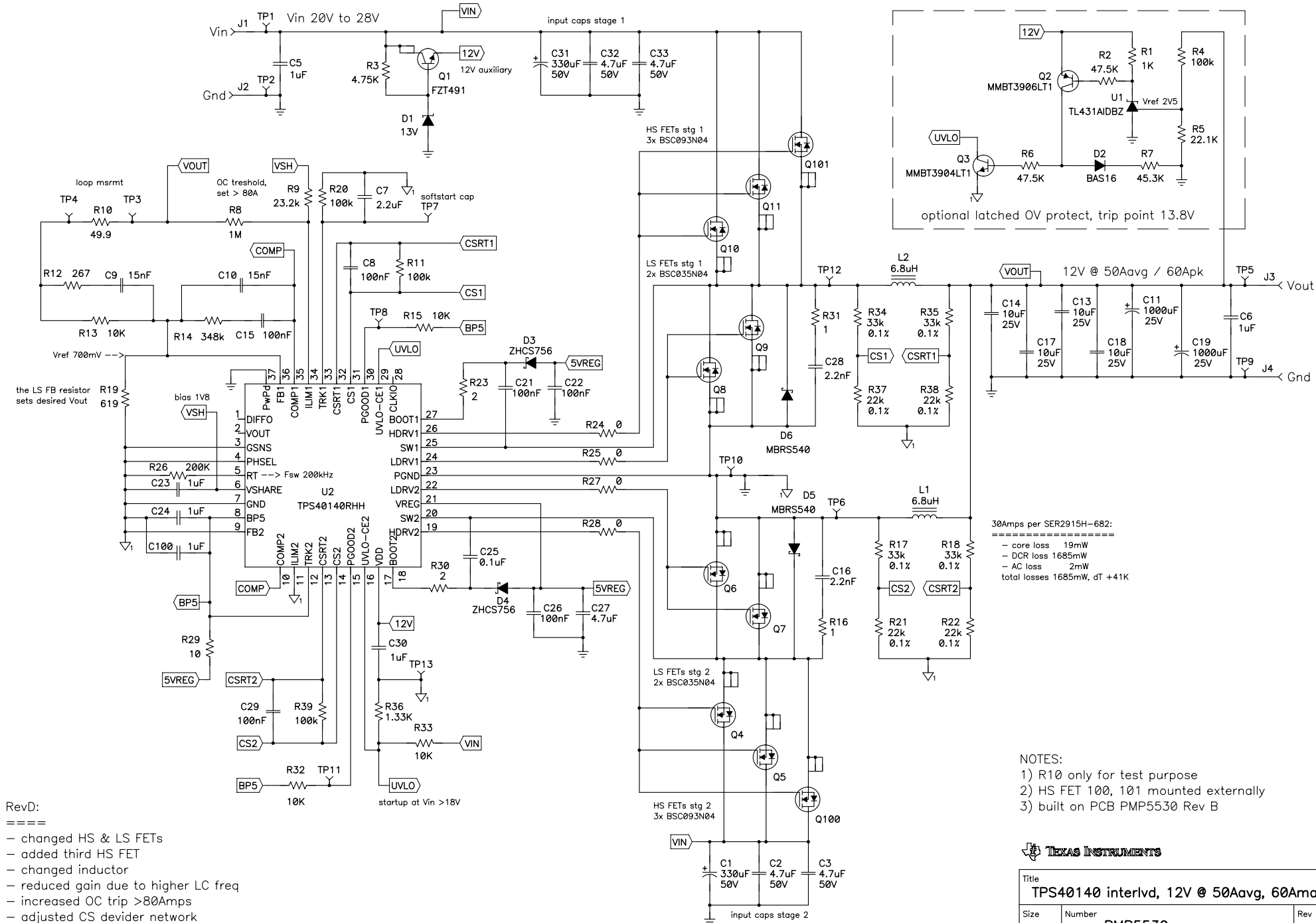


RevD:

=====

- changed HS & LS FETs
- added third HS FET
- changed inductor
- reduced gain due to higher LC freq
- increased OC trip >80Amps
- adjusted CS divider network
- C100 backpacked C24



30Amps per SER2915H-682:
 =====
 - core loss 19mW
 - DCR loss 1685mW
 - AC loss 2mW
 total losses 1685mW, dT +41K

NOTES:

- 1) R10 only for test purpose
- 2) HS FET 100, 101 mounted externally
- 3) built on PCB PMP5530 Rev B



Title TPS40140 interlvd, 12V @ 50Aavg, 60Amax		Rev D
Size C	Number PMP5530	
Date 09/03/2010	Drawn by B.Geck	
Filename PMP5530RevD.sch	Sheet 1	of 1

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